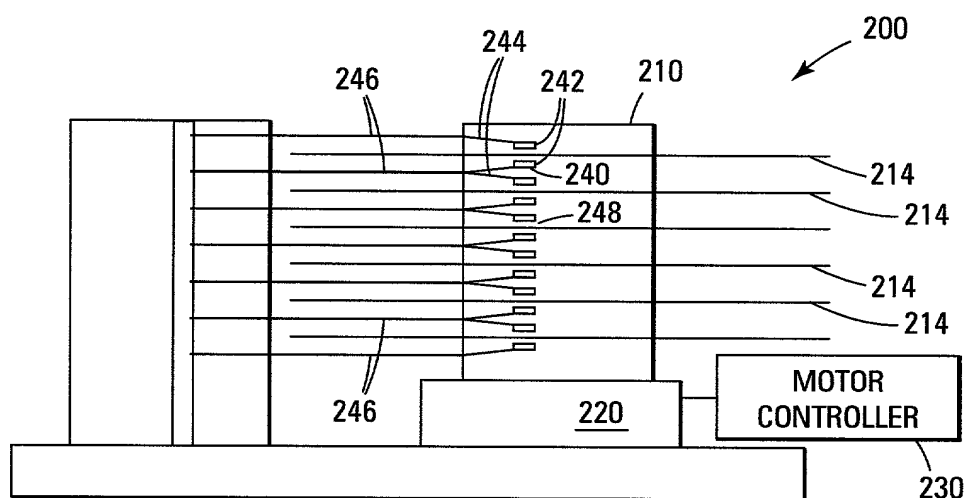


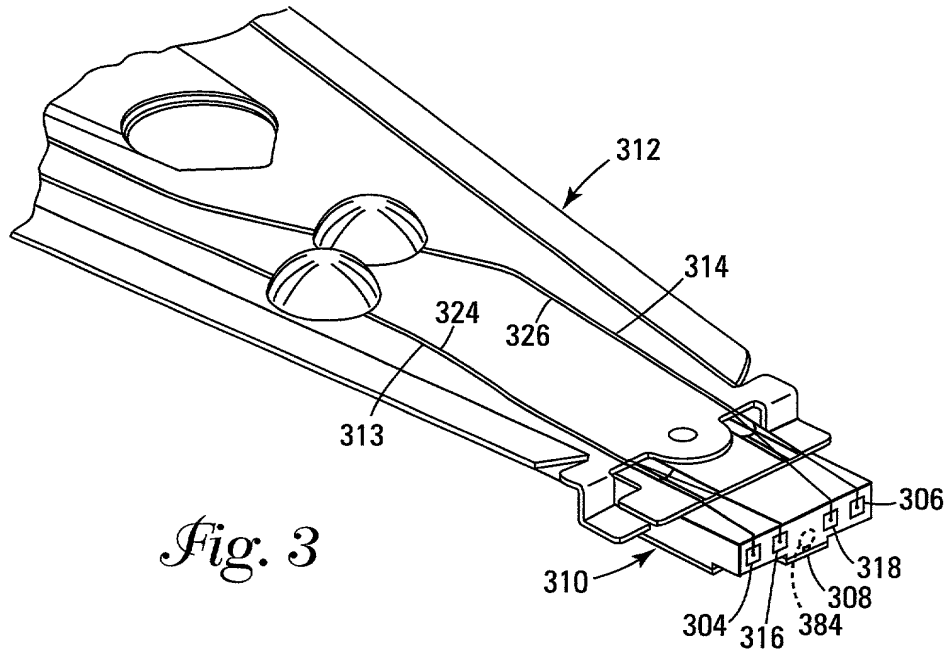
*Fig. 1*

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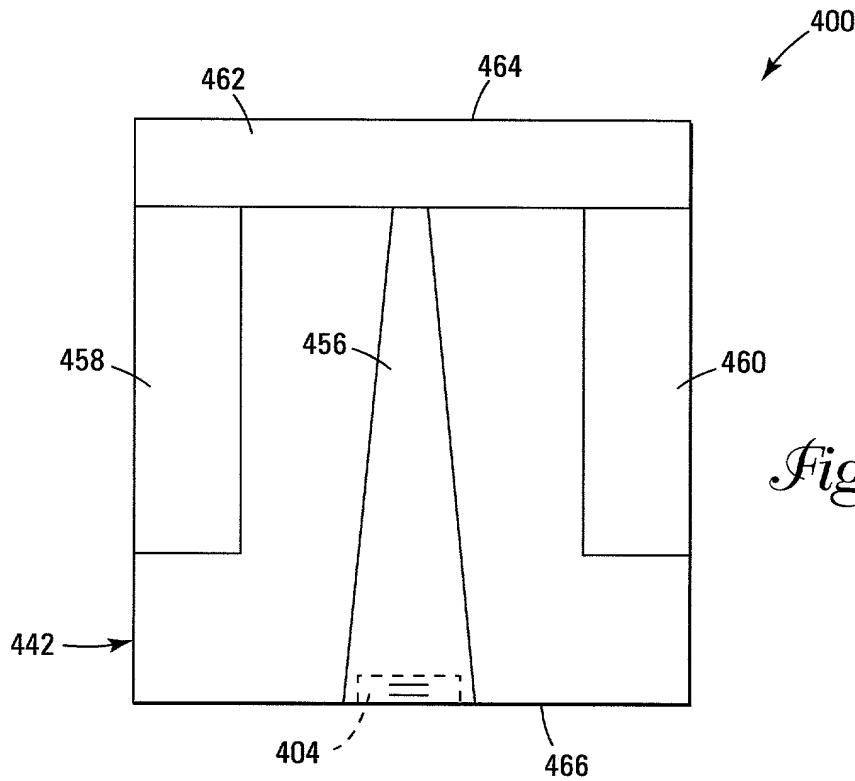


*Fig. 2*

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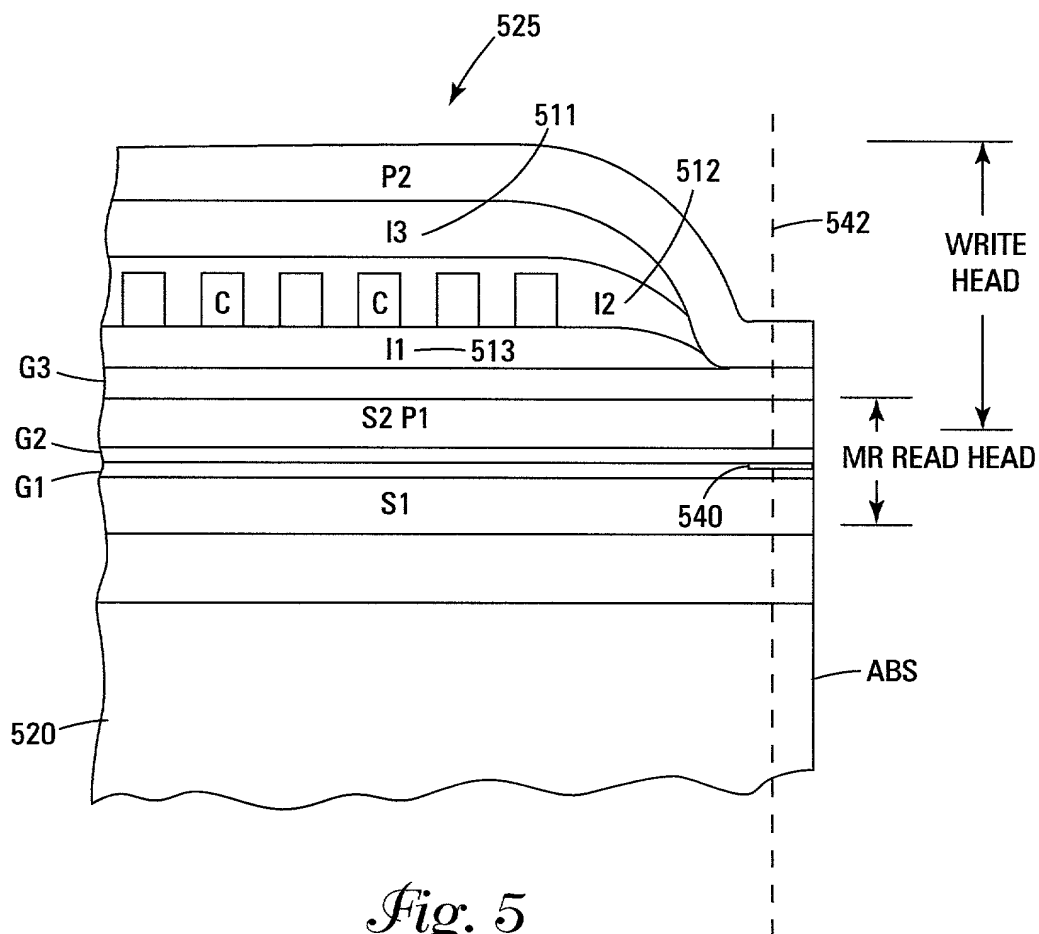


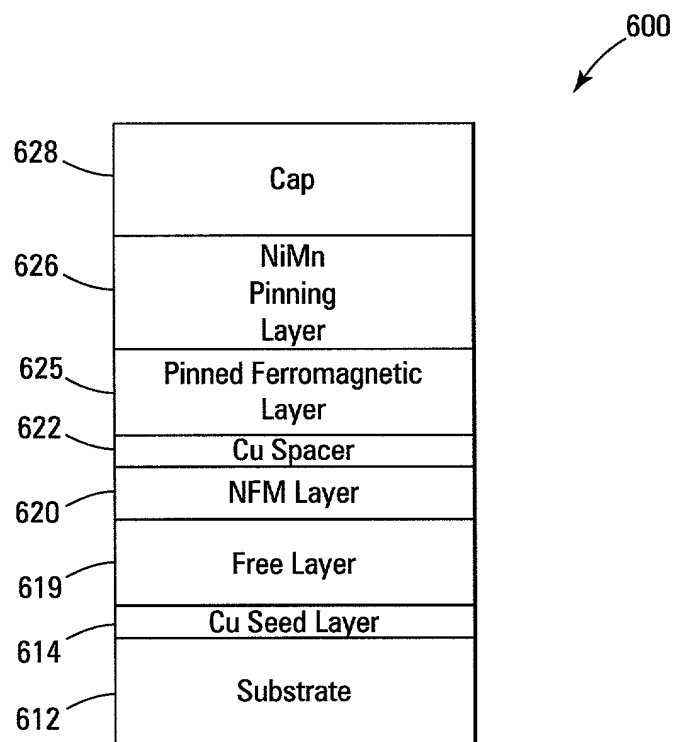
*Fig. 3*



*Fig. 4*

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*Fig. 6*

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	As-deposited free layer		Annealed free layer at 250°, 5 hrs	
	$\lambda_i$	$\lambda_b$	$\lambda_i$	$\lambda_b$
Without oxidation	$6 \times 10^{-5} \text{ \AA}$	$-3.2 \times 10^{-6} \text{ \AA}$	$8 \times 10^{-5} \text{ \AA}$	$-0.9 \times 10^{-6} \text{ \AA}$
With Cu seed and spacer oxidation	$4 \times 10^{-5} \text{ \AA}$	$-3.1 \times 10^{-6} \text{ \AA}$	$4 \times 10^{-5} \text{ \AA}$	$-1.5 \times 10^{-5} \text{ \AA}$

*Fig. 7*

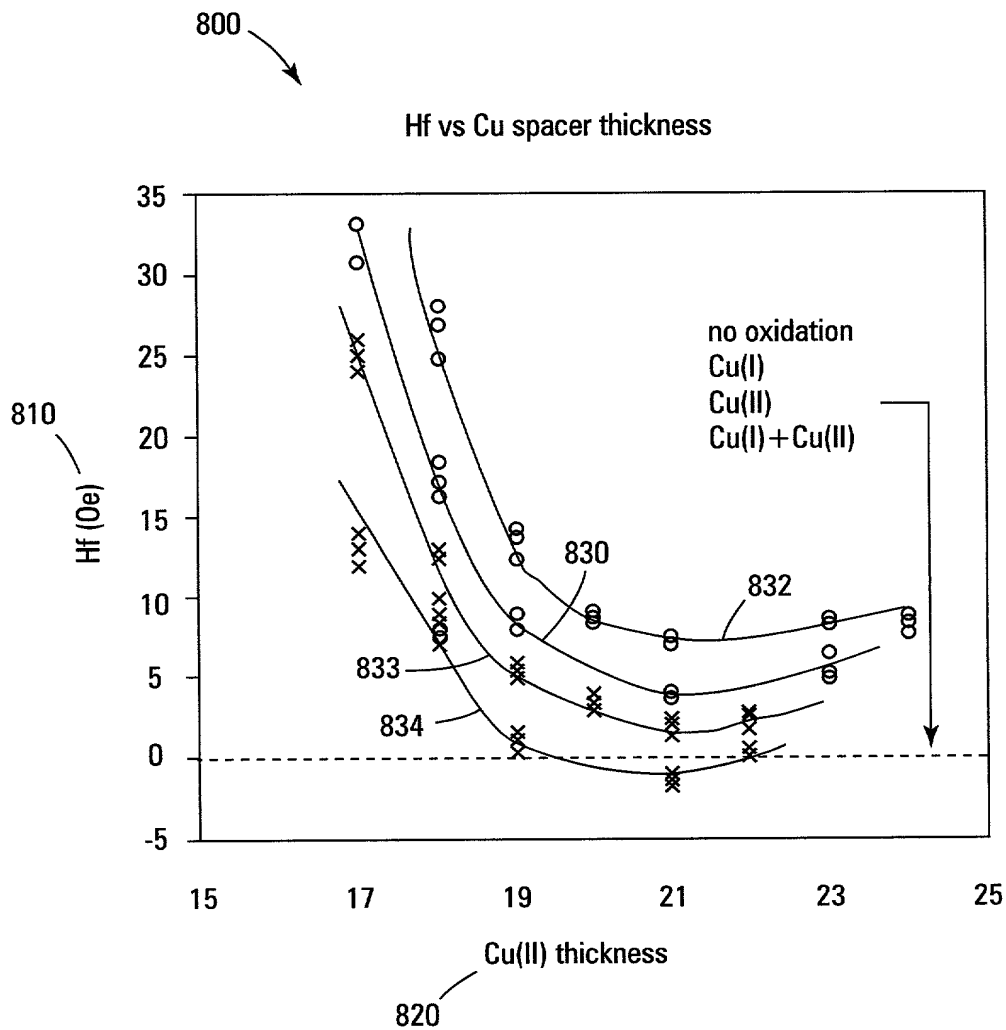
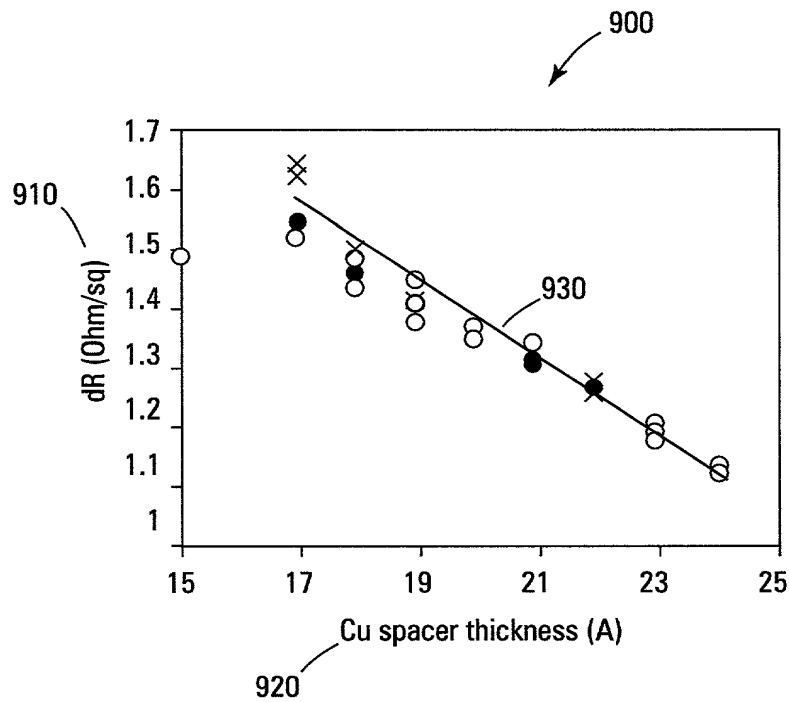


Fig. 8



*Fig. 9*



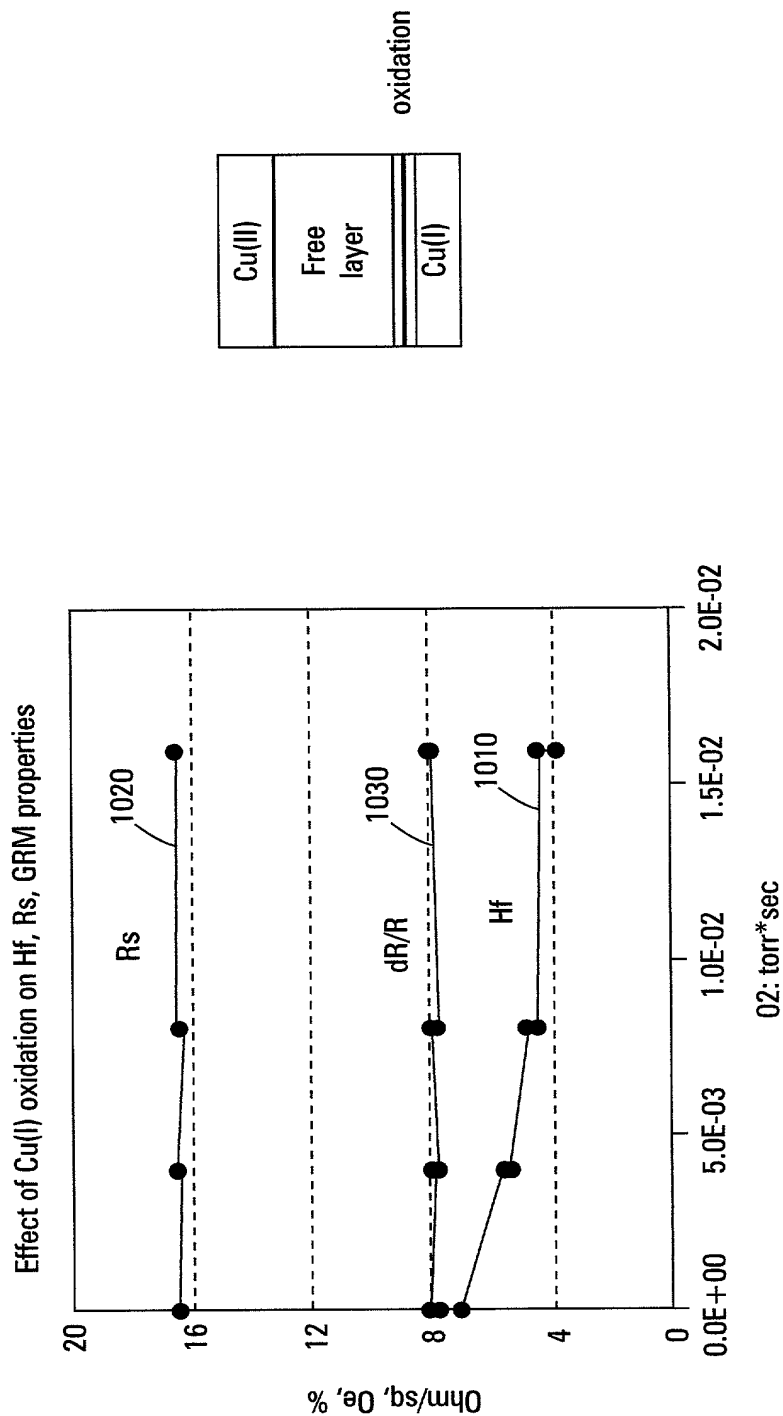


Fig. 10

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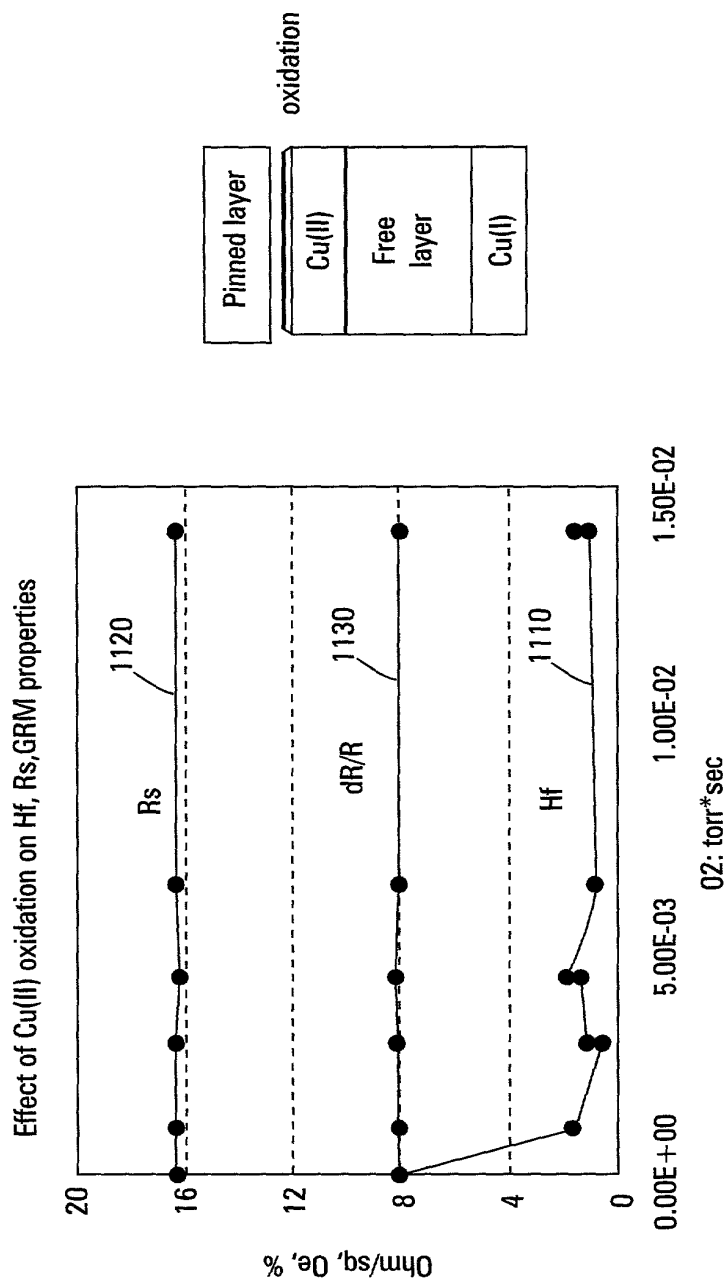
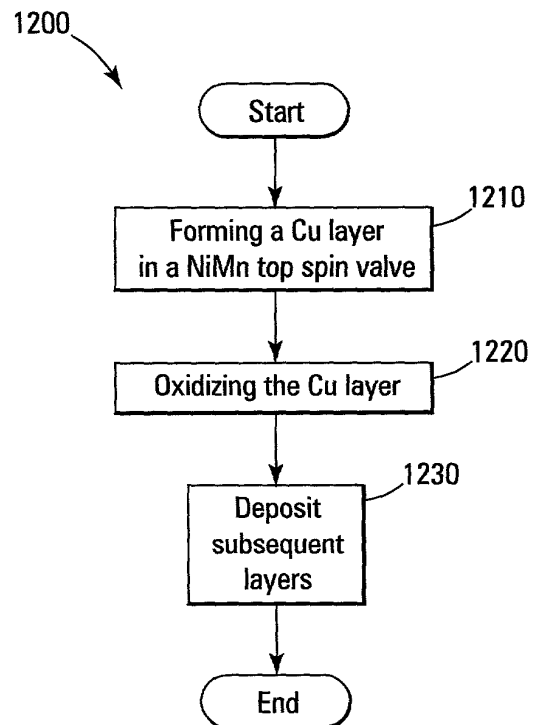


Fig. 11



*Fig. 12*